Translation

PATENT COOPERATION TREATY



PCT

INTERNATIONAL PRELIMINARY EXAMINATION REPORT

(PCT Article 36 and Rule 70)

pplicant's or agent's file reference NE-70135WO	FOR FURTHER ACTION See Notification of Transmittal of International Preliminary Examination Report (Form PCT/IPEA/416)			
nternational application No. PCT/JP2003/016034	International filing date (date 15 December 2003 (Priority date (day/month/year) 16 December 2002 (16.12.2002)	
nternational Patent Classification (IPC) or no H01L 29/812, 21/338				
Applicant	NEC CORPOR	ATION		
and is transmitted to the applicant a	ccording to Afficie 30.		national Preliminary Examining Authority	
2. This REPORT consists of a total of This report is also accompar amended and are the basis for 70.16 and Section 607 of the These annexes consist of a total of	nied by ANNEXES, i.e., she or this report and/or sheets or Administrative Instruction	ets of the descript containing rectific s under the PCT).	ion, claims and/or drawings which have been ations made before this Authority (see Rule	
3. This report contains indications rel	ating to the following items			
IV Lack of unity of in V Reasoned stateme citations and explain VI Certain document VII Certain defects in	t of opinion with regard to revention In tunder Article 35(2) with anations supporting such states the international application	regard to novelty, itement	step and industrial applicability inventive step or industrial applicability;	
VIII Certain observation	ons on the international app			
Date of submission of the demand 15 December 2003 (15.12.2003)		Date of completion 06	on of this report September 2004 (06.09.2004)	
Name and mailing address of the IPEA/J	P	Authorized office	er -	
Facsimile No.		Telephone No.		

INTERNATIONAL PRELIMINARY EXAMINATION REPORT

International application No.

PCT/JP2003/016034

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	A1	4ai-	to the language, all the elements marked above were available or furnished to this Authority in the language in which anal application was filed, unless otherwise indicated under this item. Into were available or furnished to this Authority in the following language which is:
			nguage of a translation furnished for the purposes of international search (under Rule 23.1(b)).
1		the la	nguage of publication of the international application (under Rule 48.3(b)).
		or 55.	•
3.	With prelin	regare minary	i to any nucleotide and/or amino acid sequence disclosed in the international application, the international examination was carried out on the basis of the sequence listing:
		conta	ined in the international application in written form.
1		filed	together with the international application in computer readable form.
1			shed subsequently to this Authority in written form.
1		furni	shed subsequently to this Authority in computer readable form.
		inter	statement that the subsequently furnished written sequence listing does not go beyond the disclosure in the national application as filed has been furnished.
			statement that the information recorded in computer readable form is identical to the written sequence listing has furnished.
4.		The	amendments have resulted in the cancellation of:
			the description, pages
		\sqcap	the claims, Nos.
1		\Box	the drawings, sheets/fig
5	. 🗀	This	report has been established as if (some of) the amendments had not been made, since they have been considered to go and the disclosure as filed, as indicated in the Supplemental Box (Rule 70.2(c)).**
- 1	in the	lacemen his rep	nt sheets which have been furnished to the receiving Office in response to an invitation under Article 14 are referred to ort as "originally filed" and are not annexed to this report since they do not contain amendments (Rule 70.16
*	* Any	replac	ement sheet containing such amendments must be referred to under item $\it 1$ and annexed to this report.

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V. Reasoned statement under Article 35(2) with regard to novelty, inventive step or industrial applicability; citations and explanations supporting such statement

atement			YES
Novelty (N)	' Claims	1-18	
• • •	Claims		NO
Inventive step (IS)	Claims	4-7, 10-13, 17	YE
	Claims	1-3, 8-9, 14-16, 18	NC
Industrial applicability (IA)	Claims	1-18	YE
	Claims		NO

2. Citations and explanations

Document 1: JP, 9-307097, A (SONY CORPORATION), 28 November 1997 (28.11.97), paragraphs [0031]~[0055], Figs. 4~9

Document 2: US, 2002-0005528, A1 (FUJITSU QUANTUM DEVICES LIMITED), 17 January

2002 (17.01.02), full text, all drawings

Document 3: JP, 2000-323495, A (SONY CORPORATION), 24 November 2000 (24.11.00),

full text, all drawings

Document 4: The Effect of Dielectric Stress on the Electrical Characteristics of AlGaN/GaN Heterostructure Field-Effect Transistors (HFETs) (W.S. TAN, ET. AL.), The 10th IEEE International Symposium on Electron Devices for Microwave and Optelectronic Applications, November 2002, pages 130-135

Document 5: JP, 2001-189324, A (RICOH COMPANY, LTD.), 10 July 2001 (10.07.01), full

text, all drawings

Document 6: JP, 2002-359256, A (FUJITSU LIMITED), 13 December 2002 (13.12.02), full text, all drawings

Claims 1-3

The subject matter of claims 1-3 does not involve an inventive step on account of document 1, document 2, and document 3 cited in the ISR.

Document 1 describes a field effect transistor comprising a group III nitride semiconductor structure with a heterojunction, source and drain electrodes formed at a separation on this semiconductor structure, a gate electrode disposed between the aforesaid source electrode and the aforesaid drain electrode, and an insulating film formed on the aforesaid group III nitride semiconductor layer. Document 2 describes a technique for increasing the voltage resistance of a field effect transistor by means of a gate electrode that has a field plate formed on an insulating film and extending in an eave-like manner to the drain electrode side. Document 3 describes a technique for reducing impurity diffusion depth randomness by covering the surface of a field effect transistor formed on a compound semiconductor with a laminated film consisting of a silicon nitride film 20 nm in thickness and a silicon dioxide film 20 nm in thickness. Employing the laminated film described in document 2 as the gate electrode of document 1 could easily be conceived by a person skilled in the art.

Claims 8-9

The subject matter of claim 8 does not involve an inventive step on account of document 1, document 2, document 4, and document 5 cited in the ISR.

Document 4 describes an example in which a silicon oxynitride film is used as the passivation film of an AlGaN/GaN heterojunction field effect transistor. Document 5 describes a technique for reducing parasitic capacitance by using an insulating film whose relative dielectric constant is 3.5 or less near the gate electrode. Employing the insulating film described in document 4 and document 5

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Supplemental Box

(To be used when the space in any of the preceding boxes is not sufficient)

Continuation of Box V.2:

as the insulating film of document 1 could easily be conceived by a person skilled in the art.

Claim 14-16, 18

The subject matter of claims 14-16 and 18 does not involve an inventive step on account of document 1 through document 6 cited in the ISR.

Document 6 describes a cap layer comprising a channel layer consisting of InxGal-xN, an electron supply layer consisting of AlyGal-yN, a contact layer consisting of an undoped AlGaN layer, and GaN. Employing the structure described in document 6 in the GaN field effect transistor of document 1 could easily be conceived by a person skilled in the art.

The subject matter of claims 4-7, 10-13, and 17 is neither described nor suggested in documents 1-6 cited in the ISR.